IPC ASSOCIATION ELECTRONIC	© Copyright 2005	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under international and Pan-American copyright conventions.		nder both le	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1		IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175x Form Typ Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				aterials and	als and Mfg Information				
Supplie	r Information						·								
Company name* Company				npany unique ID			Unique ID Authority				Respo	Response Date*			
onsemi											2025-0	2025-05-12			
Contact N	lame	Title - Contact			P	Phone - Contact*				Email	Email - Contact*				
Product-l	Env-Stewards		Product Enviro Compliance			1	NA				Prod	Product-Env-Stewards@onsemi.com			
uthorize	ed Representative*	Title - Representative			P	Phone - Representative*				Email	Email - Representative*				
Product-	Env-Stewards	Product Enviro Compliance			1	NA				Prod	Product-Env-Stewards@onsemi.com				
	Requester Item Number Mfr Item		n Number Mfr Item Name				Effective Date	Version	n M	Manufacturing Site		Weight*	UOM	Unit Type	
		FCD600N65S3R0 SUPERFET3 650V		V DPAK PKG		2025-05-12 CNJ		NJ		291.831	mg	Each			
Ianufa	ecturing Process Inform					-									
	8		, and the same of		-STD-020 MSL	Rating			ody Temperature Max Time at Peak		1.	1.		cles	
	Matte Tin (Sn) - annealed	[(CU Alloy	1			260		C	30	sec	onds 3			
omments															
	naximum time at peak tempera														
or more	information regarding materi	al composition	please refer t	o page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale app										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	es per the definition above except for selected exemp	otions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		'Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	astislav Drska	-6_								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.93	mg	Supplier	Silicon (Si)	7440-21-3		2.93	mg
Die Attach Solder	2.353	mg	Supplier	Silver (Ag)	7440-22-4		0.0588	mg
			A	Lead (Pb)	7439-92-1	7a	2.1765	mg
			Supplier	Tin (Sn)	7440-31-5		0.1176	mg
Lead Frame	150.208	mg	Supplier	Tin (Sn)	7440-31-5		0.1503	mg
			В	Nickel (Ni)	7440-02-0		0.1503	mg
			Supplier	Copper (Cu)	7440-50-8		149.9073	mg
Mold Compound-Black	133.6	mg		Epoxy resin	proprietary data		8.016	mg
			Supplier	Phenolic Resin	Proprietary Data		8.016	mg
			Supplier	Carbon Black (C)	1333-86-4		0.668	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		113.56	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		3.34	mg
Plating	1.9	mg	Supplier	Tin (Sn)	7440-31-5		1.9	mg
Wire Bond - Al	0.84	mg	Supplier	Aluminum (Al)	7429-90-5		0.84	mg